

IN THE CLAIMS:

Claims 1-7 (canceled).

Claim 8 has been amended as follows:

--8. (currently amended) A semiconductor device having a mounting surface [that is to be] attached to a circuit board, the device comprising:

plural reinforcing pads on said mounting surface of said semiconductor device that are each adjacent to a respective corner of said mounting surface; and

plural first solder balls on each of said reinforcing pads, each of said plural first solder balls separately attaching the semiconductor device to the circuit board,

wherein said reinforcing pads each [having] have a periphery adjacent to said plural ones of said first solder balls that, when seen in a plan view of said mounting surface, is at least semicircular.--

--9. (previously added) The device of claim 8, wherein said reinforcing pads are generally X-shaped and have four of said first solder balls thereon, each of said four first solder balls being at a respective distal end thereof.

--10. (previously added) The device of claim 8, wherein said reinforcing pads are generally V-shaped and have at least two of said first solder balls thereon, each of said at least two first solder balls being at a respective distal end thereof.

--11. (previously added) The device of claim 8, further comprising plural second solder balls on said mounting surface and not on said reinforcing pads.

--12. (previously added) The device of claim 8, wherein said periphery of said reinforcing pads adjacent to said plural ones of said first solder balls, when seen in the plan view of said mounting surface, is no more than semicircular.--